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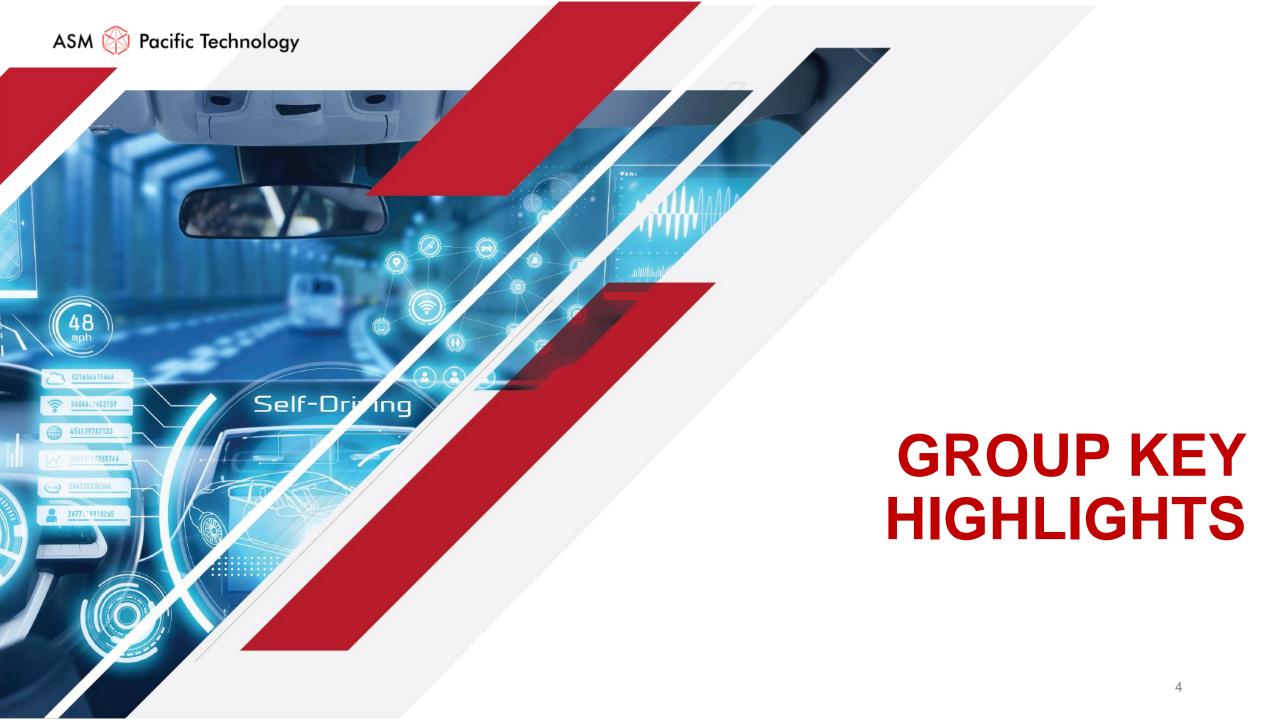
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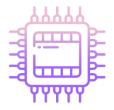
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Record Q1 Revenue Amid Continued Supply Chain Challenges



Advanced Packaging Momentum Underpins Strong Group Bookings



Strong Q1 Demand for Automotive Solutions



Unique and Broad Product Portfolio's Competitive Advantage

Record Q1 Revenue Amid Continued Supply Chain Challenges

(-15.1% QoQ) (+21.5% YoY)

US\$675M US\$903M

(+34.2% QoQ) (-69 bps QoQ) (-10.0% YoY) (+107 bps YoY)

40.6%

(-97 bps QoQ) (+361 bps YoY)

19.1%



Revenue



Bookings

%

Gross Margin



Operating Margin



Backlog



Net Profit¹

9/0

EPS

US\$1.52B

(+26.9% YoY) (+18.2% QoQ) HK\$830M

(+57.1% YoY) (-15.0% QoQ) HK\$2.02

(+59.1% YoY)

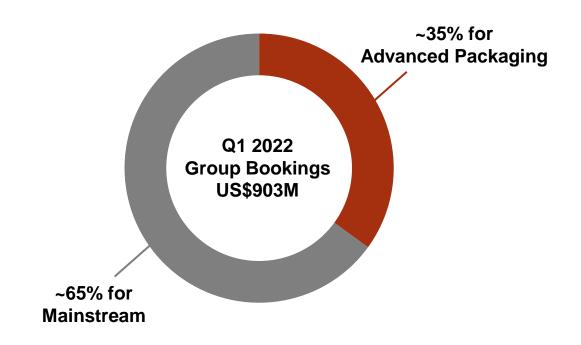
(-9.0% QoQ)



Motos

¹ excluding one-off items of HK\$65.0 million and their related tax charge of HK\$0.5 million recorded in Q4 2021 amounting to HK\$65.5 million

Advanced Packaging Momentum Underpins Strong Group Bookings



Strong orders in Q1 22

- TCB
- Mid-end Deposition
- SMT system-in-package ("SiP") printing and placement
- Advanced Displays (Mini LED placement)
- Laser dicing and grooving
- Photonics placement

Drivers

- HPC applications
- Demanding requirements for ultra-fine pitch Mini LED RGBs
- Increasingly advanced SiP requirements for consumer and communication applications



TCB



Mid-end Deposition



SMT SiP Printing and Placement



Advanced Displays (Mini LED placement)



Laser Dicing and Grooving

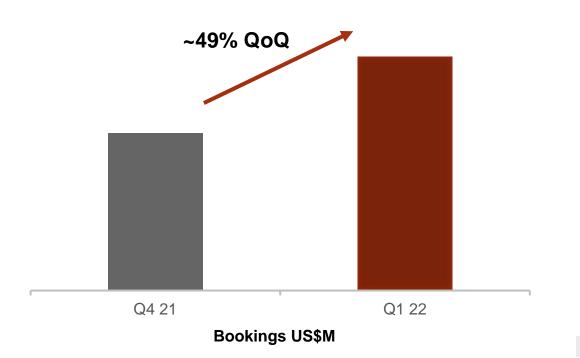


Photonics Placement

Strong Q1 Demand for Automotive Solutions

Comprehensive Solutions to Address Automotive Market

- Bookings for Automotive solutions grew ~49% QoQ
- Spanning both SEMI and SMT Automotive tools
- Riding on global momentum for automotive electrification



Silver Sintering Solutions Power Module Advanced Packaging Solutions





Automotive CIS Solutions



Vehicle LiDAR Module





In-Vehicle Micro LED Display

Die/Wire Bond & Mold



Power Discrete Packages Analog, Logic, MCUs

*Automotive solutions provided by ASMPT

Self-Drive Computing Board

Unique Broad-Based Portfolio's Competitive Advantage

Strong Tailwinds

Long-Term Secular Growth Drivers

(5G / AI / Advanced Displays / Automotive / HPC / IoT)

Addressable Market Expansion

Advanced Packaging: US\$2.7B (2026)

(21-26F CAGR: 11%)² **Automotive: US\$2.9B** (2026)

(21-26F CAGR: 9%)²

Bullish Growth of Total Semiconductor Devices 1.6 Trillion Units (2026)

(20-26F: CAGR: 9.3%)1

Unique Broad-based Portfolio

Mainstream & Applicative Tools

Volume Leverage + Cash Generators

Mainstream

Die & Wire Bonders, Test Handlers and Encapsulation tools

Mainstream

SMT Printing and Placement

Applicative

Camera Module, Lens Attach and Active Alignment

Advanced Packaging Tools

High Growth + High Margin

Mid-End

Deposition and Laser Dicing

Ultra-Precision Placement

Mini/Micro LED, TCB and Hybrid Bonding

System-in-Package

Die Bonder and SMT Placement

Software Solutions for Smart Manufacturing

Long-Term Performance

Less Cyclical Revenue and Profitability

> Structural Revenue Growth and Margin Expansion

¹ VLSIresearch Worldwide Semiconductor History and Forecast, December 2021

² Company Management's Estimates

Unique Broad-Based Portfolio Effects on Q1 Performance

Unique Broad-based Portfolio

Mainstream & Applicative Tools

Volume Leverage + Cash Generators

Mainstream

Die & Wire Bonders, Test Handlers and Encapsulation tools

Mainstream

SMT Printing and Placement

Applicative

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Software Solutions for Smart Manufacturing

Effects on Q1 2022 Performance

SMT Bookings grew QoQ for Two Consecutive Quarters

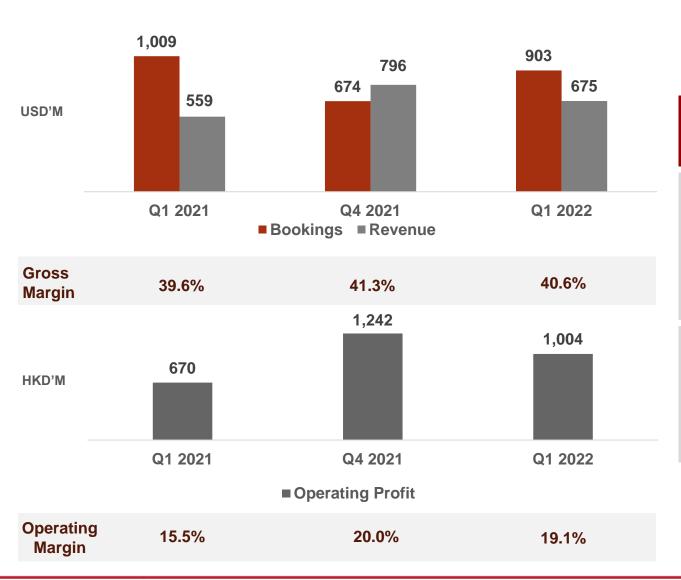
SMT Revenue grew QoQ, Bucking Usual Q4 to Q1 Trend

(SMT activity typically picks up several quarters after SEMI)

Strong Demand for Group's AP tools Underpinned Q1 Group Bookings Momentum



Q1 2022 Group Financial Results



Record Q1 Revenue

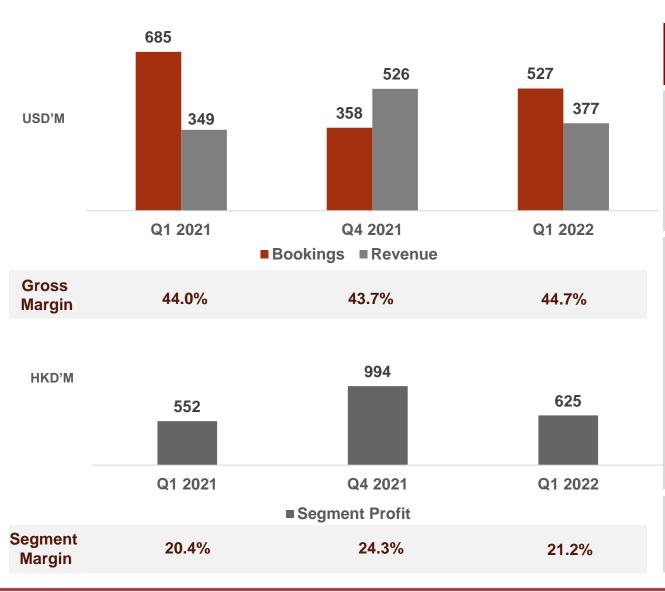
Q1 22 Bookings:

- Strong bookings underpinned by Advanced Packaging and Automotive
- Book-to-bill ratio: 1.34

Drivers for YoY margins improvement:

- Strong SEMI and SMT gross margin despite cost pressures
- Record Q1 revenue

Q1 2022 Semiconductor Solutions Segment Performance



Positive QoQ and YoY Gross Margin Growth

Q1 Bookings:

- QoQ growth drivers: Advanced Packaging & Automotive tools
- YoY decline due to record high base in Q1 21

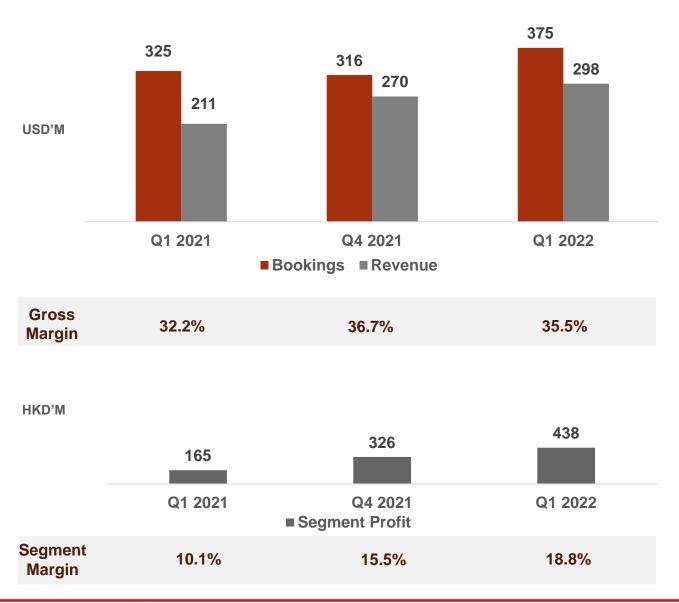
Q1 Revenue:

- IC/Discrete
 - Record Q1 revenue
 - Die and wire bonders & encapsulation tools dominated deliveries
- Optoelectronics
 - Conventional & advanced displays, general lighting and photonics applications accounted for majority of deliveries
- CIS
 - Declined YoY and flat QoQ largely due to soft market conditions for smartphones

Gross Margin:

QoQ and YoY improvement on product mix (relatively higher mix of automotive applications)

Q1 2022 SMT Solutions Segment Performance



Record Q1 Bookings

Q1 Bookings:

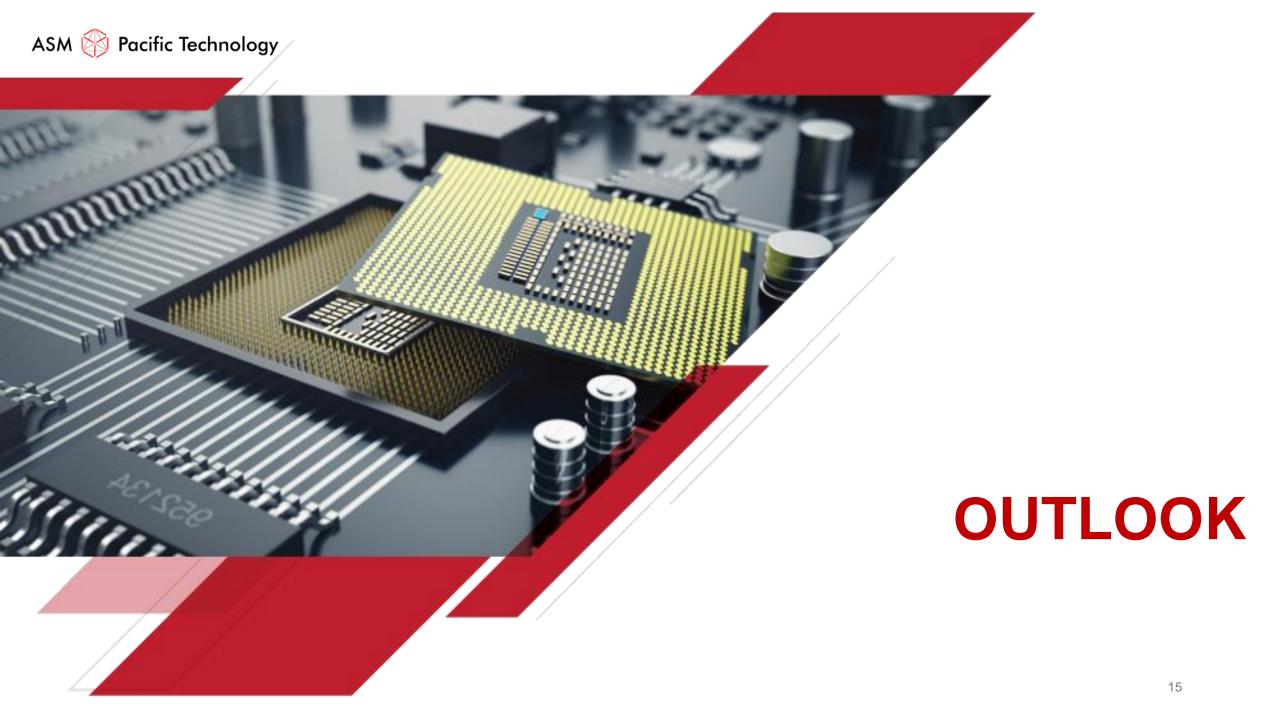
- QoQ and YoY increase
- Advanced Packaging and automotive grew QoQ and YoY

Q1 Revenue:

- Sequential revenue growth bucked typical trends
- Mainstream high-end printing and placement tools grew QoQ and YoY
- YoY growth in Advanced Packaging SiP placement tools

Gross Margin:

YoY improvement on volume effect and product mix



Outlook



US\$670m to US\$740m

(+5.8% YoY and +4.5% QoQ at mid-point of guidance)



While the Group has taken steps to convert its strong order backlog at a faster pace, sporadic COVID-19 measures, and continued supply chain constraints could influence near-term deliveries

Long Term Prospects



Group is well-positioned to capture substantial share of investments over long term

- Strong industry tailwinds and secular growth trends
- Long-term structural growth in semiconductor device unit volumes
- Bullish multi-year capital investments of leading semiconductor companies



